

N-Ch 150V Fast Switching MOSFETs

Description:

- Advanced Trench MOS Technology
- Low Gate Charge
- Low $R_{DS(ON)}$
- 100% EAS Guaranteed
- Green Device Available



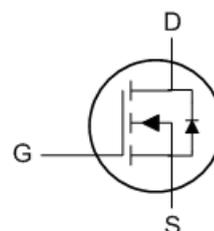
TO220 Pin Configuration

Applications:

- Load Switch
- LED Applications
- Networking Applications
- Quick Charger

Product Summary

| BVDSS | R _{DS(ON)} | I _D |
|-------|---------------------|----------------|
| 150V | 9mΩ | 100A |



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|------------------------|---|------------|-------|
| V_{DS} | Drain-Source Voltage | 150 | V |
| V_{GS} | Gate-Source Voltage | ±20 | V |
| $I_D@T_C=25^{\circ}C$ | Continuous Drain Current, V_{GS} @ 10V ¹ | 100 | A |
| $I_D@T_C=100^{\circ}C$ | Continuous Drain Current, V_{GS} @ 10V ¹ | 63 | A |
| I_{DM} | Pulsed Drain Current ² | 400 | A |
| EAS | Single Pulse Avalanche Energy ³ | 784 | mJ |
| I_{AS} | Avalanche Current | 56 | A |
| $P_D@T_C=25^{\circ}C$ | Total Power Dissipation ⁴ | 178 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | °C |
| T_J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ¹ | --- | 50 | °C/W |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ¹ | --- | 0.7 | °C/W |

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---------------------|--|---|------|------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250uA | 150 | --- | --- | V |
| R _{DS(ON)} | Static Drain-Source On-Resistance ² | V _{GS} =10V, I _D =20A | --- | 7.3 | 9 | mΩ |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =250uA | 2 | 3 | 4 | V |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =120V, V _{GS} =0V, T _J =25°C | --- | --- | 1 | uA |
| | | V _{DS} =120V, V _{GS} =0V, T _J =55°C | --- | --- | 5 | |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} =±20V, V _{DS} =0V | --- | --- | ±100 | nA |
| R _g | Gate Resistance | V _{DS} =0V, V _{GS} =0V, f=1MHz | --- | 1.9 | --- | Ω |
| Q _g | Total Gate Charge | V _{DS} =75V, V _{GS} =10V, I _D =20A | --- | 100 | --- | nC |
| Q _{gs} | Gate-Source Charge | | --- | 24.9 | --- | |
| Q _{gd} | Gate-Drain Charge | | --- | 30.8 | --- | |
| T _{d(on)} | Turn-On Delay Time | V _{DD} =30V, V _{GS} =10V, R _G =3.3Ω, I _D =1A | --- | 32 | --- | ns |
| T _r | Rise Time | | --- | 25 | --- | |
| T _{d(off)} | Turn-Off Delay Time | | --- | 97 | --- | |
| T _f | Fall Time | | --- | 89 | --- | |
| C _{iss} | Input Capacitance | V _{DS} =75V, V _{GS} =0V, f=1MHz | --- | 5870 | --- | pF |
| C _{oss} | Output Capacitance | | --- | 404 | --- | |
| C _{riss} | Reverse Transfer Capacitance | | --- | 9.3 | --- | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|--|---|------|------|------|------|
| I _S | Continuous Source Current ¹ | V _G =V _D =0V, Force Current | --- | --- | 100 | A |
| V _{SD} | Diode Forward Voltage ² | V _{GS} =0V, I _S =1A, T _J =25°C | --- | --- | 1.2 | V |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=50V,V_{GS}=10V,L=0.5mH,I_{AS}=56A
- 4.The power dissipation is limited by 150°C junction temperature.
- 5.The data is theoretically the same as I_D and I_{DM}, in real applications , should be limited by total power dissipation.

Typical Characteristics

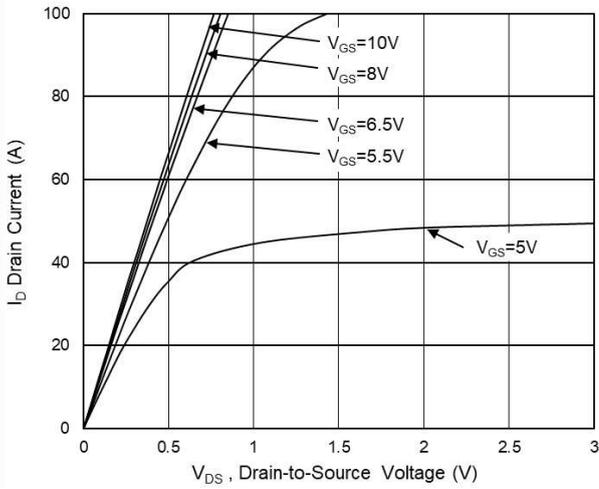


Fig.1 Typical Output Characteristics

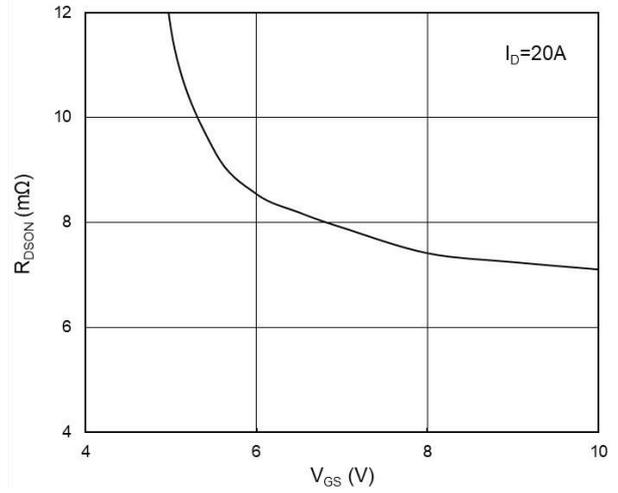


Fig.2 On-Resistance vs G-S Voltage

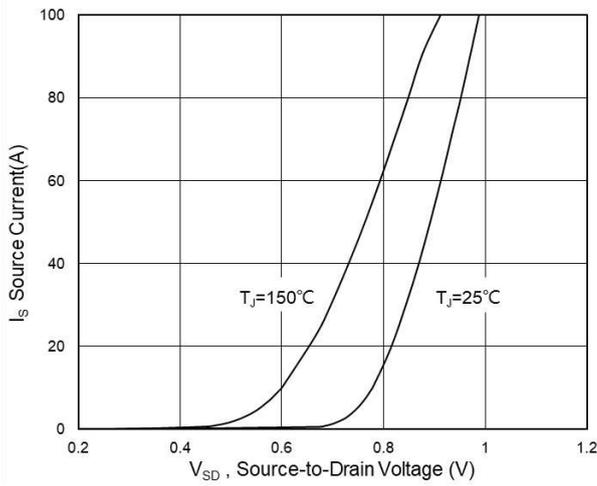


Fig.3 Source Drain Forward Characteristics

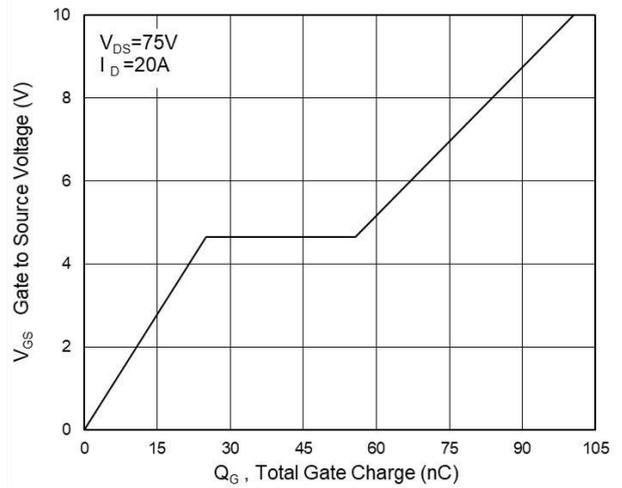


Fig.4 Gate-Charge Characteristics

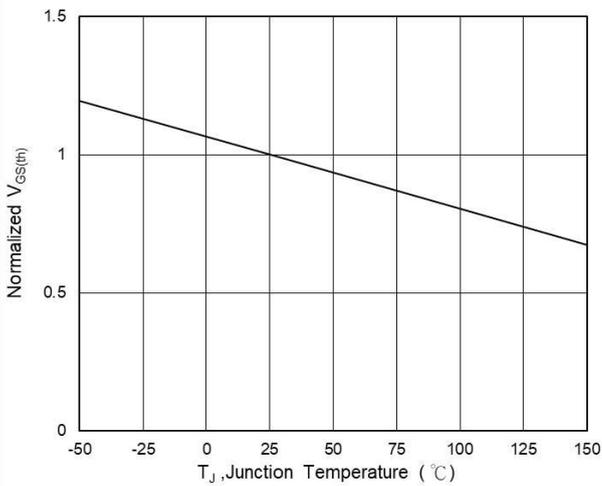


Fig.5 Normalized $V_{GS(th)}$ vs T_J

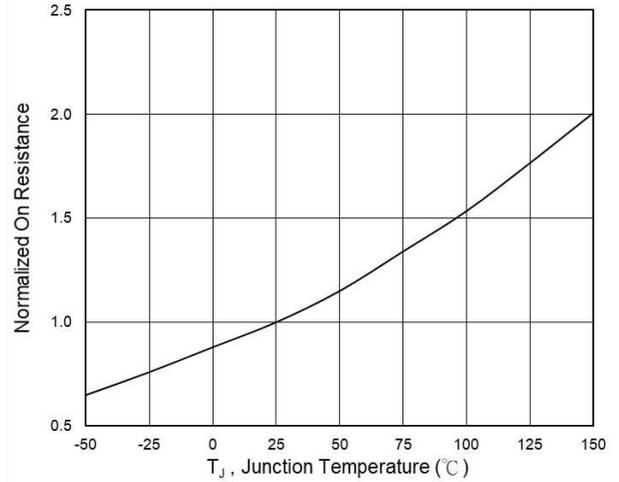


Fig.6 Normalized $R_{DS(on)}$ vs T_J

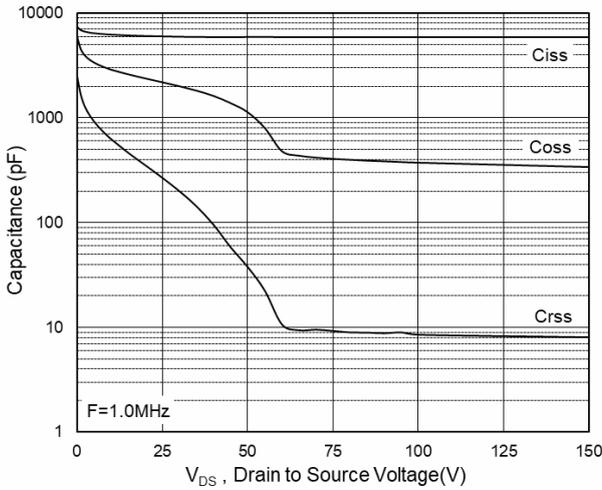


Fig.7 Capacitance

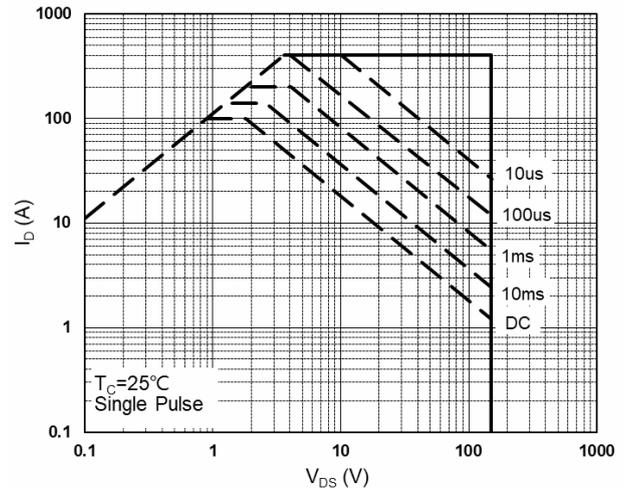


Fig.8 Safe Operating Area

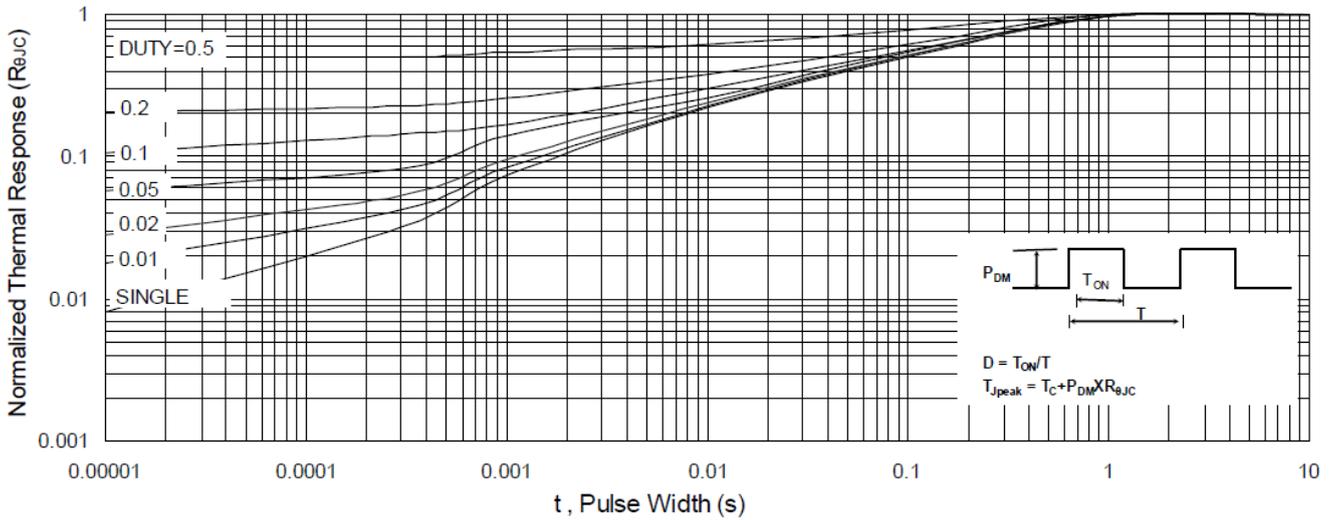


Fig.9 Normalized Maximum Transient Thermal Impedance

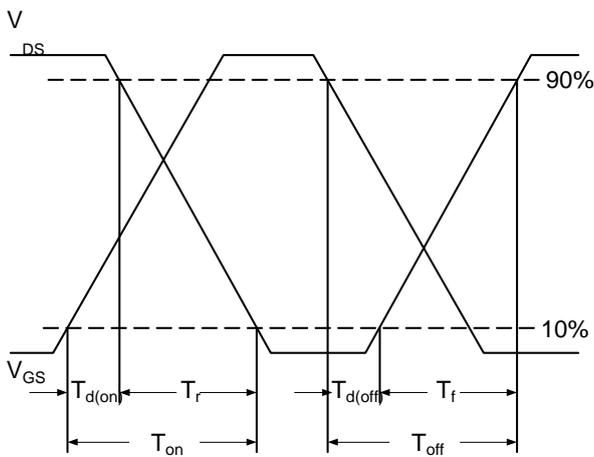


Fig.10 Switching Time Waveform

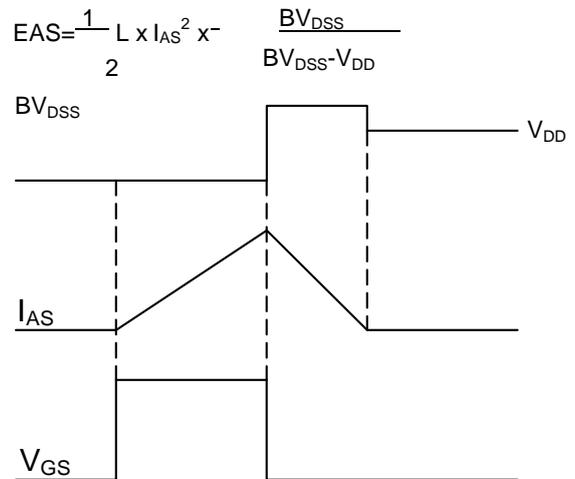


Fig.11 Unclamped Inductive Switching Waveform